



Material Content Data Sheet



Sales Product Name		BTM7750G		Issued		20. July 2018		
MA#		MA001364448						
Package		PG-DSO-28-22		Weight*		810.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.033	1.36	1.36	13614	13614
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		89	
	non noble metal	zinc	7440-66-6	0.288	0.04		355	
	non noble metal	iron	7439-89-6	5.754	0.71		7100	
wire	non noble metal	copper	7440-50-8	233.637	28.83	29.59	288282	295826
	non noble metal	aluminium	7429-90-5	1.651	0.20	0.20	2037	2037
	encapsulation	organic material	carbon black	1333-86-4	1.098	0.14		1355
encapsulation	plastics	epoxy resin	-	78.542	9.69		96911	
	inorganic material	silicondioxide	60676-86-0	469.602	57.94	67.77	579436	677702
leadfinish	non noble metal	tin	7440-31-5	4.975	0.61	0.61	6138	6138
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	836	836
glue	plastics	epoxy resin	-	0.546	0.07		673	
	noble metal	silver	7440-22-4	2.573	0.32	0.39	3174	3847
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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